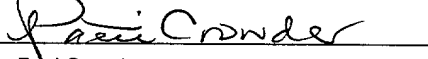


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Patti Crowder

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In the application of:

Benjamin N. Eldridge et al.

Application No.: 09/452,255

Filing Date: May 26, 1995

For: ELECTRICAL CONTACT STRUCTURES  
FORMED BY CONFIGURING A FLEXIBLE  
WIRE TO HAVE A SPRINGABLE SHAPE  
AND OVERCOATING THE WIRE WITH AT  
LEAST ONE LAYER OF A RESILIENT  
CONDUCTIVE MATERIAL, METHODS OF  
MOUNTING THE CONTACT STRUCTURES  
TO ELECTRONIC COMPONENTS, AND  
APPLICATIONS FOR EMPLOYING THE  
CONTACT STRUCTURES

Examiner: C. Arbes

Group Art Unit: 3729

**COMMUNICATION**

Box: Patent Application  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Please note that the inventors residence addresses have changed as follows:

1. Benjamin N. Eldridge  
651 Sheri Lane  
Danville, California 94526
2. Gary W. Grube  
6807 Singletree Court  
Pleasanton, California 94588

3. Igor Y. Khandros  
25 Haciendas Road  
Orinda, California 94563
4. Gaetan L. Mathieu  
659 Orange Way  
Livermore, California 94550

Entry of the above-information is hereby respectfully requested.

Respectfully submitted,

Date: December 21, 2000

By: 

Stuart L. Merkadeau  
Registration No. 33,262

FormFactor, Inc.  
Legal Department  
5666 La Ribera St.  
Livermore, CA 94550  
925-294-4300  
925-294-8147 Fax

08/452255

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE  
FEE RECORD SHEET

PTO-1556  
(5/87)

ELECTRICAL CONTACT STRUCTURES FORMED BY CONFIGURING A FLEXIBLE WIRE TO HAVE A SPRINGABLE SHAPE AND OVERCOATING THE WIRE WITH AT LEAST ONE LAYER OF A RESILIENT CONDUCTIVE MATERIAL, METHODS OF MOUNTING THE CONTACT STRUCTURES TO ELECTRONIC COMPONENTS, AND APPLICATIONS FOR EMPLOYING THE CONTACT STRUCTURES

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